

CLIPPEDIMAGE= JP401008647A

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TITLE: MANUFACTURE OF SEMICONDUCTOR DEVICE

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INVENTOR-INFORMATION:

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ABSTRACT:

PURPOSE: To directly form a bump on an electrode without base metal by forming a recess on the bump, feeding conductive paste which contains as a main ingredient at least one of Cu, Ag and Au therein, aligning the bump with the electrode, then bonding it to the electrode, and thereafter curing the paste to bond a semiconductor chip to a substrate.

CONSTITUTION: The depth of a recess 20 is required to be 1/10 or higher of the height of a bump. Its size is desired to be 1/2 or less by calculating it with its remaining area. The center of an electrode is coated in advance with resist so as not to bond an Au-plating or Cu-plating. After it is Au-plated to form the bump, a recess may be formed by pressing. Then, a chip 1 with a bump

4 is placed on a substrate 7 uniformly coated with paste 6. After it is coated with the paste, the bump is etched or wiped to remove the remaining paste. Thereafter, the electrode 2 of the chip 1 is aligned to the electrode 8 of a lead 9, and bonded.

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